DS50PCI401, DS64BR401

Driving High-Speed Signals in Data Center Servers and Storage Area Networks

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Driving High-Speed Signals in Data Center Servers and Storage Area Networks

— Lee Sledjeski, Applications Engineer

With less capital available for continuous system "upgrades", new data center solutions must be space- and energy-efficient while supporting multi-faceted expansion to keep ahead of users' data storage needs. Engineers are leveraging open industry standards like PCI Express (PCle) and SAS/SATA to create efficient architectures that address current and future data center requirements. With only limited input and output signal conditioning written directly into these standards, hardware design has been constrained by cable and PCB attenuation of high-speed serial data. Even within a single rack of equipment, signals that remain on backplanes will exhibit losses beyond those detailed in the PCle standard.

This article explains how a pair of National’s new PowerWise® 4-lane bi-directional transceivers (DS50PCI401 and DS64BR401) directly address interconnect attenuation challenges with capabilities beyond standards-dictated signal conditioning. PCle 2.0 sets a maximum transmit de-emphasis of 6 dB and SAS recommends 3 dB. However, PCle cable assembly response indicates that 12 dB of compensation is needed to optimize 7m 24 AWG cable performance. Similar loss compensation will be needed for 24” to 30” backplane traces commonly found in server designs today. The DS50PCI401 transceiver provides a gain of up to 26 dB for PCle applications, while the DS64BR401 transceiver provides a gain of up to 33 dB for SAS/SATA and other high-speed signaling technologies.

Working with PCle and SAS/SATA standards can pose some additional challenges for silicon products designed to extend data transmission distances. Multiple sideband signals, remote detection mechanisms, and high-level signaling techniques such as out-of-band (OOB) and Beacon need to be properly handled to ensure robust initiator – target or root complex – endpoint-state machine synchronization.

PCle-Specific Communication

PCI Express links can be broken down into two distinct operating environments; namely, a PCle external cable or a backplane slot. Within a PCle cable, several sideband signals have been defined and must be implemented. They include CPWRON, CPERST#, and CPRSNT#. Depending on the system design, several options for hardware control are possible. CPWRON is an indication for the upstream system that its supply voltage rails have achieved the minimum nominal value. CPERST#, short for cable platform reset, provides the downstream subsystem with an indication of the reset state from the upstream subsystem. CPRSNT# is a response from the downstream subsystem that it is indeed present and its power supply is functioning within nominal limits.
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Using the cabling environment (shown in Figure 1) as an example, initial communication from the downstream subsystem to the upstream subsystem is achieved with the CPRSNT# auxiliary signal. The CPRSNT# signal is asserted Low by the downstream circuitry after the "Power Good" condition has been established. This mechanism allows for the upstream subsystem to determine whether the power is good within the downstream subsystem, enable the reference clock, and initiate the link training sequence.

The auxiliary signals could be easily replicated within the downstream subsystem and used to control the RXDETA/B inputs on the DS50PCI401 transceiver. Often an onboard microcontroller will be used to handle events like power-up, power-down, power-saving modes, and hot insertion. The microcontroller would use the same information to determine when to enable and disable the DS50PCI401 input termination. In applications that require SMBus control, the microcontroller could also delay any response to the upstream subsystem to allow sufficient time to correctly program the DS50PCI401 transceiver and other devices on the board.

Prior to software configuration of the PCIe link, the PCIe transmitter (Tx) will enact a receiver (Rx) detection process, as shown in Figure 1. The detection process begins with the Tx invoking a common-mode shift above the GND potential onto its high-speed outputs. When a Rx is present, the Rx will interact with and terminate the common-mode voltage shift. Circuitry that monitors the response must be able to decipher between the terminated (Rx present) and unterminated (Rx absent) conditions. Control over the DS50PCI401 Rx termination can be achieved directly through the RXDETA/B inputs.

![Figure 1. PCIe Cabling Event Timing](image-url)
In backplane applications using the PCIe standard, all of the auxiliary signals may not be present. In order to facilitate some high-level communication between the root complex and endpoint, PCIe has defined a signaling technique called Beacon. Beacon is a slow (30 KHz to 500 MHz) signal sent on at least Lane 0 of the high-speed serial data bus. The objective of sending a Beacon signal is to request the reapplication of power and exit the L2 or low-power state. This operation can also be achieved using the WAKE# sideband signal. Although Beacon is an optional signal that does not need to be implemented in systems operating at GEN2 or 5 Gbps, older GEN1 devices may necessitate its ongoing support. In order to pass a Beacon signal, the DS50PCI401 device must have the 50W input terminations “active”. Otherwise the Beacon signal will not be retransmitted on the DS50PCI401 outputs.

Additional methods of communication that are used in backplane/server applications include a subset of sideband signals such as PRSNT# or physical mechanisms such as a manual retention latch (MRL).

**SAS/SATA-Specific Communication**

Without auxiliary signals to convey state-change information, the SAS/SATA high-speed signal path doubles as a low-speed communication port. Like a modern form of Morse code, Out-Of-Band (OOB) signaling (Figure 2) is a series of signal burst, idle, and negation times transmitted and detected across a SAS/SATA link. Link initiators and targets use this information to begin communication and establish link protocol. For the DS64BR401 transceiver, the key OOB-related specifications are the active-to-idle and idle-to-active propagation delays which are closely matched to minimize any OOB-signaling envelope distortion.

![Figure 2. Nominal Out-of-Band Signal Timing](image-url)
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The desired outcome of SAS/SATA OOB signaling is to move the physical layer State Machines into the speed-negotiation and identification-sequence states. For SAS-to-SAS communication, the target device responds to COMSAS with COMSAS. For SAS-to-SATA connections, the SATA target will not respond to COMSAS. This difference allows the initiating device to proceed as a SAS host or emulate a SATA host.

The SAS speed-negotiation sequence seeks to establish physical link communications at the highest possible transmission rate. No longer initiator and target, the SAS speed-negotiation sequence is a peer-to-peer communication. The rules for speed negotiation are the same for both participating devices, with the outcome being robust bidirectional communication at the highest speed possible for the initiator – interconnect – target combination.

Standard-Based Signal Conditioning

PCIe and SAS/SATA have kept performance statements about transmit and receive equalization to a minimum requirement. While this has made the implementation easier and kept the costs low for a general case, it will not work in every desired application. As designers push PCIe across the entire system at GEN2 speeds and users demand higher-speed storage, signal attenuation across system interconnects becomes a common issue.

There are two primary mechanisms that result in frequency-dependent loss in cables and PCB traces.

1. **Skin Loss**: Skin effect causes most of the high-frequency current to travel on the outer surface (skin) of the conductor. Consequently, the effective resistance of the conductor increases with frequency. Skin loss is directly proportional to the square root of signal frequency resulting in a more gradual frequency roll-off.

2. **Dielectric Loss**: As the signal travels in a conductor that is insulated from another by a dielectric material, some of the signal gets absorbed by the dielectric material. Dielectric loss is directly proportional to signal frequency resulting in a steeper frequency roll-off.

Both skin loss and dielectric loss degrade the edge rate of high-frequency binary signals in the same fundamental way by introducing Inter Symbol Interference (ISI) spreading the energy from a single bit over multiple-bit periods, Figure 3.

PCIe 2.0 sets a maximum transmit de-emphasis of 6 dB; SAS recommends 3 dB while clearly stating increased margins may be obtained by deviating from the recommended values. PCIe cable assembly response indicates that 12 dB of compensation is needed to optimize 7m 24 AWG cable performance. Similar loss compensation will be needed for 24” to 30” backplane traces commonly found in server designs today. The DS50PCI401 and DS64BR401 transceivers clearly meet and exceed these demands.
**De-Emphasis Performance**

In order to support multiple generations of a serial standard with an optimal signal conditioning response, it is vital to understand the underlying data rate of the signal passing through the device. Internal device circuitry detects PCIe 2.5/5.0G and SAS/SATA 3.0/6.0G operation and adjusts the output DE pulse width accordingly. For 100% compliance with PCIe and SAS/SATA electrical specifications, both devices include settings designed to the individual standards.

In *Figure 4*, a detailed oscilloscope waveform shows different styles of De-Emphasis (DE) with approximately 6 dB of gain. The ideal DE pulse width will quickly reach maximum amplitude, but decay over a slightly longer period of time. This analog de-emphasis behaves in a manner very similar to the multi-tap design of a high-speed digital serializer, producing maximum gain at the Nyquist frequency and reduced gain as the frequency decreases. This technique best approximates and compensates for attenuation in the transmission media.

**Signal conditioning devices play a critical role in compensating for media loss.** At multi-Gbps speeds, attenuation in cables and PCB traces can impact communication within and between systems. Robust communication can be maintained by employing input and output signal conditioning techniques on lossy interconnects. Since the PCIe and SAS/SATA standards utilize full-duplex high-speed signaling paths, the DS50PCI401 and DS64BR401 signal conditioning devices offer both receive equalization and transmit de-emphasis (EQ and DE) techniques in a single IC.

*Figure 5* shows typical results using the DS50PCI401 device in a backplane/server application. To emulate the backplane, 28" of 5-mil 100W differential stripline are attached to the transceiver evaluation board via short 50W SMA cables.

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*Figure 4. De-Emphasis Waveforms for 2.5G and 5.0G Operation*

- **Media:** 28" FR4 stripline
- **Setting:** -12 dB output de-emphasis
- **Vertical eye opening:** 170 mV
- **Media attenuation:** -11.5 dB at 1.25 GHz
- **Data rate:** 5.0 Gbps with a PRBS7 pattern
- **Total jitter (peak-peak):** 25.0 ps

*Figure 5. DS50PCI401 Output Signal Conditioning*
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**Equalization Performance**
Unfortunately, simply having the ability to equalize long cables or large backplanes is not enough. The equalizer setting must be easy to set and forgiving to different data rates and even cable lengths. The DS50PCI5401 Continuous Time Linear Equalization (CTLE) will not need to be retuned or adjusted for each data rate. Perhaps it is a design cycle upgrade or a mix of old and new cards in a server, but multiple data rates may be present in many systems. The setting for 2.5 Gbps is also the setting for 5.0 Gbps. This, in conjunction with the automatic de-emphasis adjustment for data rate, allows dynamic PCIe and SAS/SATA speed negotiation to take place without altering any signal conditioning settings on the link.

As the data rate across an interconnect increases, so does the attenuation. *Figure 6* shows the complete eye closure and decreased low-frequency amplitude as the speed increases from 2.5 Gbps to 5.0 Gbps. Optimal signal recovery at both data rates is achieved by selecting the equalization setting that best matches media attenuation at 2.5 GHz as shown in *Figure 7*.

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**Figure 6. Attenuation vs. Data Rate in FR4**

<table>
<thead>
<tr>
<th>Media: 42&quot; FR4 stripline</th>
<th>Media attenuation: -10.2 dB at 1.25 GHz</th>
<th>Equalization setting: 17 dB at 2.5 GHz</th>
<th>Datarate: 2.5 Gbps with a PRBS7 pattern</th>
<th>Total jitter (peak-peak): 29.0 ps</th>
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<tbody>
<tr>
<td>Media: 42&quot; FR4 stripline</td>
<td>Media attenuation: -17.6 dB at 2.5 GHz</td>
<td>Equalization setting: 17 dB at 2.5 GHz</td>
<td>Datarate: 5.0 Gbps with a PRBS7 pattern</td>
<td>Total jitter (peak-peak): 33.0 ps</td>
</tr>
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</table>

**Figure 7. Multi-Rate Equalization**

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For external cabling applications, designers may be forced to select one equalization setting to compensate for multiple cable lengths. The equalization setting is more critical and the received signals smaller as cable lengths increase. PCIe cables provide some built-in compensation for length. Short cables are built with 28 AWG wires which increase the attenuation per unit length. The longer cables use 24 AWG wire to minimize losses, thereby reducing the overall change in attenuation between the shortest and longest cable assemblies.

The input design of both transceivers contains an active equalizer. As the name implies, the design uses active transistors to gain up signals at high frequencies without attenuating low frequencies. This equalization scheme works well even when low-signal amplitudes are expected at the equalizer input, providing for an extended compensation envelope and enabling longer, lighter cable assemblies to be utilized. In addition, most active equalizers can tolerate high-input amplitudes equally well, providing good flexibility when the cable length is unknown. Figure 8 highlights this flexibility showing equalizer response to PCIe cable assemblies one to ten meters in length. The results are achieved without adjusting the equalizer setting, allowing designers to specify use of multiple cable lengths without the need to reprogram any system firmware.
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Beyond the EQ setting used in Figure 8, National’s transceivers can provide, via pin or SMBus control, up to 10 dB of additional input equalization at 3.0 GHz. With the ability to compensate for more attenuation, a designer can specify cable assemblies with smaller gauge wire. Lighter cable reduces strain on connectors and chassis and allows for increased cable density and enhanced cable flexibility in tight installations.

Design for Success
Successful recovery of attenuated signals involves much more than just a good equalizer; it actually starts with the transmitter. Having a transmitter with low output jitter is pretty obvious, but equally important is having good return-loss characteristics. All primary waveforms on the link begin at the transmitter; at this point in the transmission media, they contain the maximum level of high-frequency harmonic content. Any energy reflected back into the transmitter can impact following data if not completely absorbed in the transmitter output structure.

Between the transmitter and receiver it is likely several opportunities exist for impedance discontinuities. Everything that can be done to minimize the size and magnitude of each discontinuity will reduce residual jitter and add margin to the system. Paying particular attention to changes in transmission structure and return-path continuity will help to ensure the best possible signal fidelity. The following list highlights and discusses several problems and strategies to address them.

Vias:
Vias are part of a link structure that are absolutely required, but would be nice to live without. Fortunately several things can be done to remove them from the ‘signal integrity radar’.

1. A return-current via should be added always to eliminate common-mode noise on the reference planes and minimize any impedance discontinuity arising from a change in the signal-reference plane.

2. Particular attention should be paid to the overall via construction as vias tend to hold excess capacitance. Spending a little time with a modeling tool should result in a stack-up that matches the impedance of the transmission line. Within a thick PCB, it is possible to create a stub with a portion of the via barrel; back drilling will extend the bandwidth of the structure.

Space:
Connectors and components are always bottlenecks for high-speed pairs. Multiple PCB layers should be used and signals should be distributed evenly to maximize the distance between signal pairs.

Symmetry:
In an ideal world everything would be perfectly symmetrical – allowing a pure differential signal at the transmitter to reach the receiver attenuated, but still remains a pure differential signal. The first step is to match the electrical length of both signals in the differential pair. The second step is to treat each trace equally; test points and other loads should have a mirror image looking from one trace to another. The most significant benefit of this extra work is reduced system EMI. Any common signal can escape easily from the product enclosure.

Conclusion
Expanding the reach of PCIe, SAS/SATA, and other serial links provides a competitive advantage to system developers. With input and output signal conditioning that works across backplanes, cable assemblies, and over multiple data rates, National’s DS50PCI401 and DS64BR401 transceivers provide designers with a flexible and efficient signal conditioning solution for today’s challenging serial link applications.

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